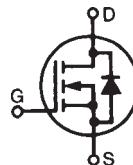


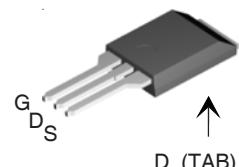
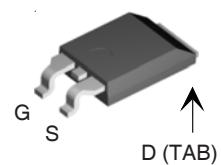
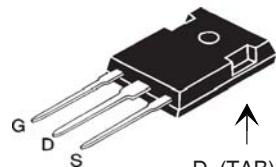
**PolarHT™ Power
MOSFET HiPerFET™**
**IXFV52N30P
IXFV52N30PS
IXFH52N30P**

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



V_{DSS} = 300V
 I_{D25} = 52A
 $R_{DS(on)}$ ≤ 66mΩ
 t_{rr} ≤ 200ns

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	300	V
V_{DGR}	T_J = 25°C to 150°C, $R_{GS} = 1\text{M}\Omega$	300	V
V_{GSS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	T_C = 25°C	52	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	150	A
I_A	T_C = 25°C	52	A
E_{AS}	T_C = 25°C	1	J
dV/dt	$I_S \leq I_{DM}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$	10	V/ns
P_D	T_C = 25°C	400	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum lead temperature for soldering	300	°C
T_{SOLD}	Plastic body for 10s	260	°C
M_d	Mounting torque (TO-247)	1.13/10	Nm/lb.in.
F_c	Mounting force (PLUS220)	11..65/2.5..14.6	N/lb.
Weight	PLUS220 & PLUS220SMD TO-247	4 6	g g

PLUS220 (IXFV)

PLUS220SMD (IXFV_S)

TO-247 (IXFH)


G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$	300		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4\text{mA}$	2.5		V
I_{GSS}	$V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$		± 100	nA
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0\text{V}$		25 1	μA mA
$R_{DS(on)}$	$V_{GS} = 10\text{V}$, $I_D = 0.5 \cdot I_{D25}$, Note 1		66	mΩ

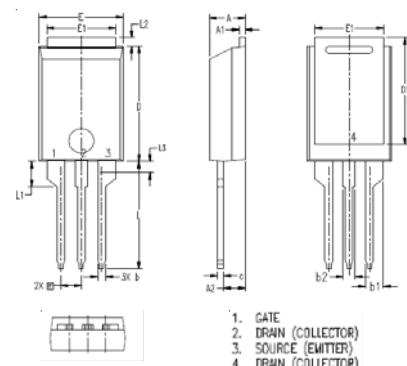
Features

- International standard packages
- Fast recovery diode
- Avalanche rated
- Low package inductance
 - easy to drive and to protect

Advantages

- Easy to mount
- Space savings
- High power density

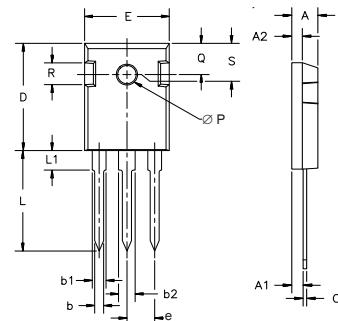
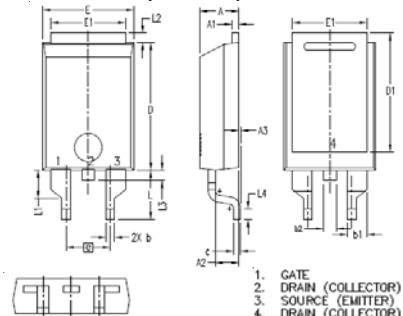
Symbol	Test Conditions ($T_J = 25^\circ\text{C}$ unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10\text{V}$, $I_D = 0.5 \cdot I_{D25}$, Note 1	20	30	S
C_{iss}		3490		pF
C_{oss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	550		pF
C_{rss}		130		pF
$t_{d(on)}$	Resistive Switching Times $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 52\text{A}$ $R_G = 4\Omega$ (External)	24		ns
t_r		22		ns
$t_{d(off)}$		60		ns
t_f		20		ns
$Q_{g(on)}$	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$	110		nC
Q_{gs}		25		nC
Q_{gd}		53		nC
R_{thJC}			0.31	°C/W
R_{thCS}	(TO-247, PLUS220)	0.25		°C/W

PLUS220 (IXFV) Outline

Source-Drain Diode
 $T_J = 25^\circ\text{C}$ unless otherwise specified)

Characteristic Values

	Min.	Typ.	Max.
I_s	$V_{GS} = 0\text{V}$		52 A
I_{SM}	Repetitive, pulse width limited by T_{JM}		150 A
V_{SD}	$I_F = I_s$, $V_{GS} = 0\text{V}$, Note 1		1.5 V
t_r	$I_F = 25\text{A}$, $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$, $V_{GS} = 0\text{V}$	160	200 ns
Q_{RM}		800	nC
I_{RM}		7	A

Note 1: Pulse test, $t \leq 300\mu\text{s}$; duty cycle, $d \leq 2\%$.

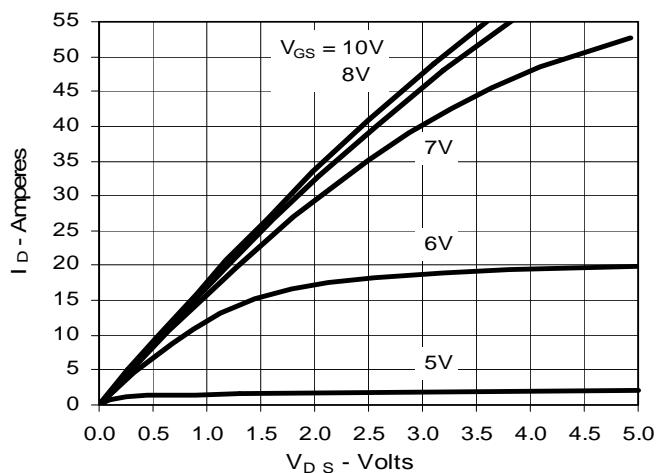
TO-247 (IXFH) Outline

PLUS220SMD (IXFV_S) Outline


SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.028	.035	0.70	0.90
A2	.098	.118	2.50	3.00
A3	.000	.010	0.00	0.25
b	.035	.047	0.90	1.20
b1	.080	.095	2.03	2.41
b2	.054	.064	1.37	1.63
c	.028	.035	0.70	0.90
D	.551	.591	14.00	15.00
D1	.512	.539	13.00	13.70
E	.394	.433	10.00	11.00
E1	.331	.346	8.40	8.80
e	.200BSC		5.08 BSC	
L	.209	.228	5.30	5.80
L1	.118	.138	3.00	3.50
L2	.035	.051	0.90	1.30
L3	.047	.059	1.20	1.50
L4	.039	.059	1.00	1.50

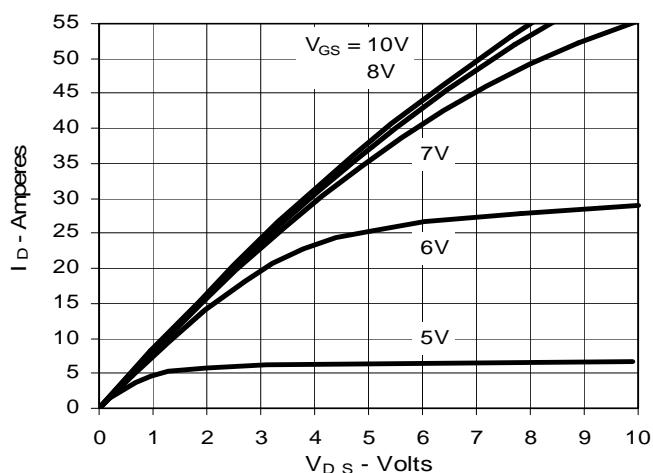
IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,850,072 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

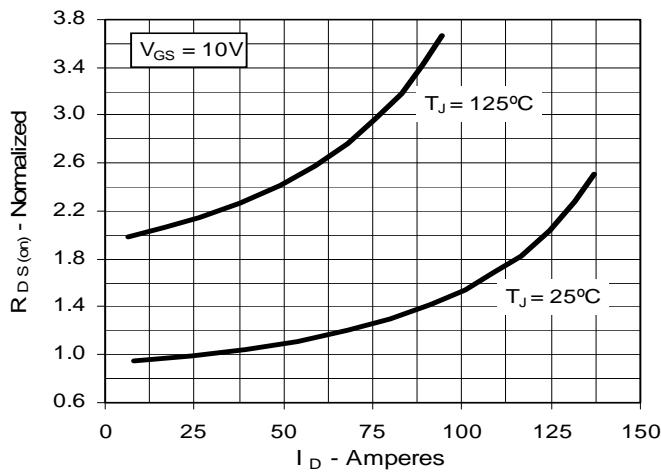
**Fig. 1. Output Characteristics
@ 25°C**



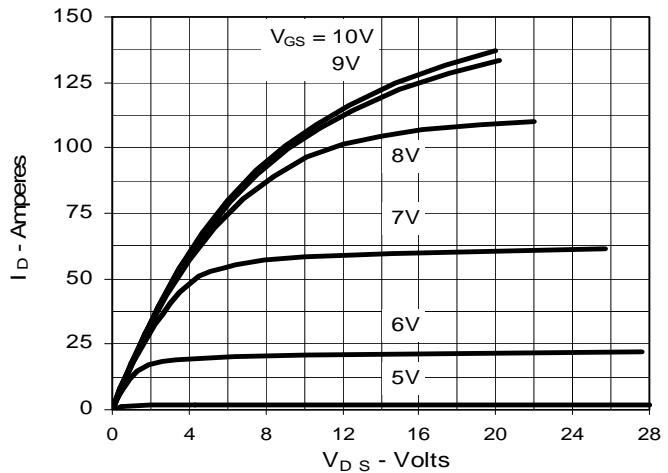
**Fig. 3. Output Characteristics
@ 125°C**



**Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 26A$ Value
vs. Drain Current**



**Fig. 2. Extended Output Characteristics
@ 25°C**



**Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 26A$ Value
vs. Junction Temperature**

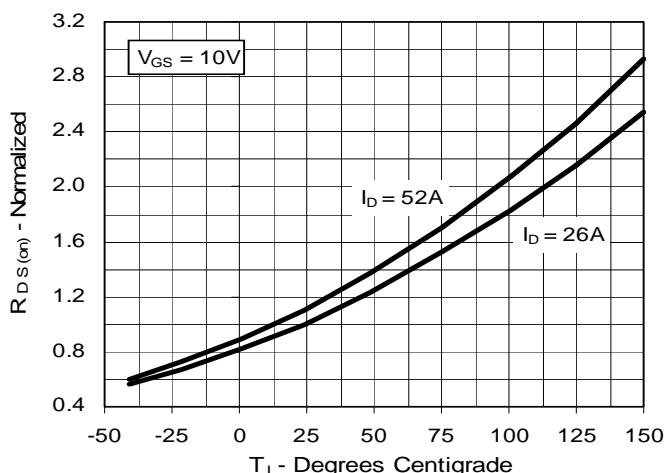


Fig. 6. Drain Current vs. Case Temperature

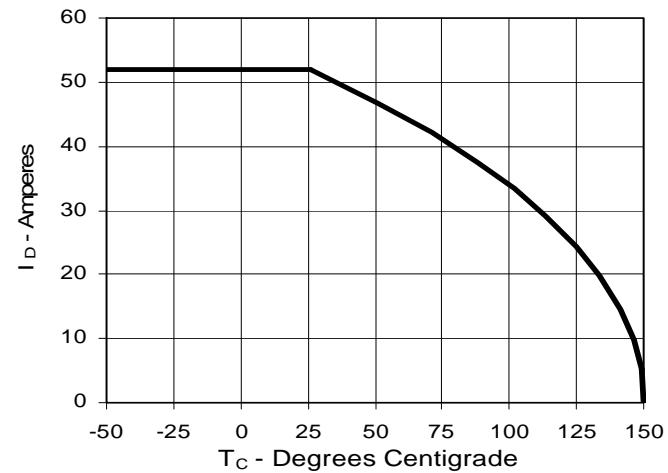


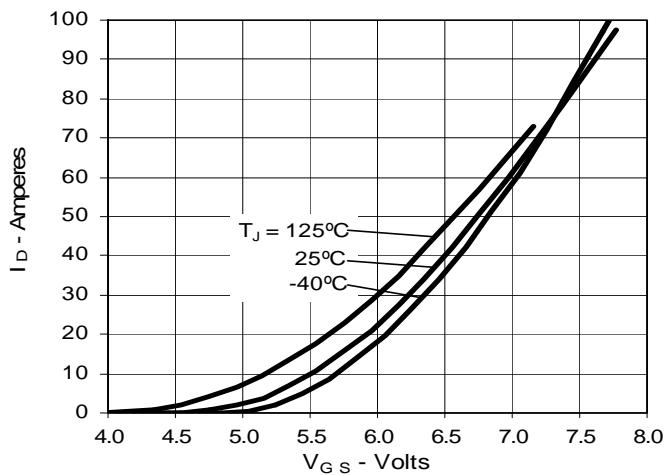
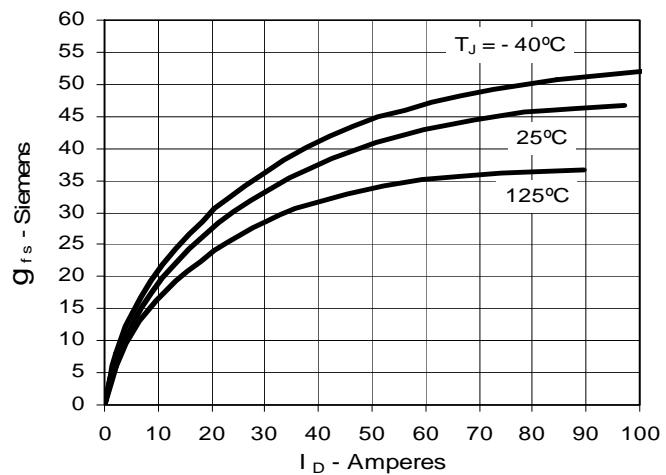
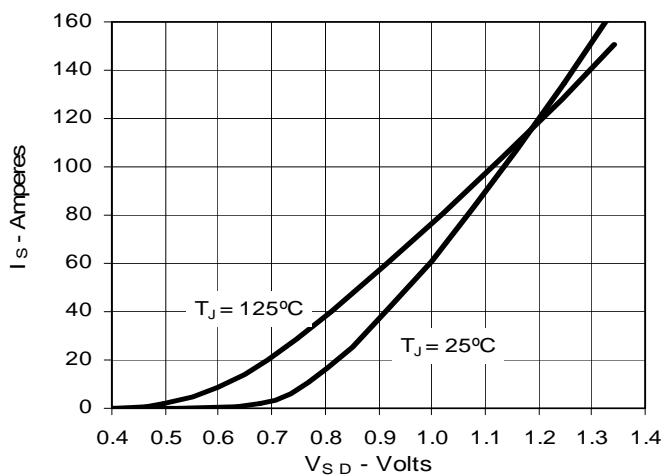
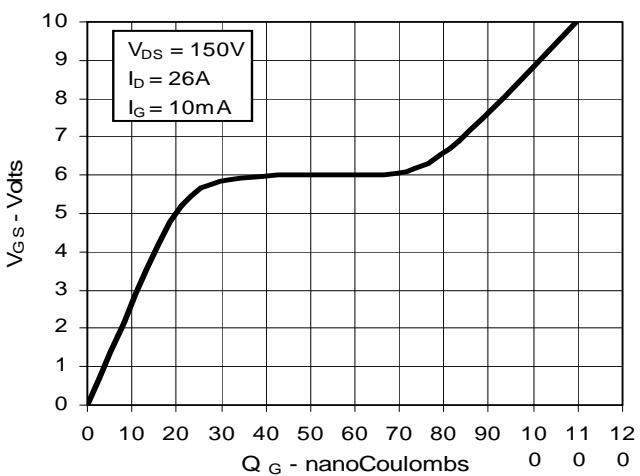
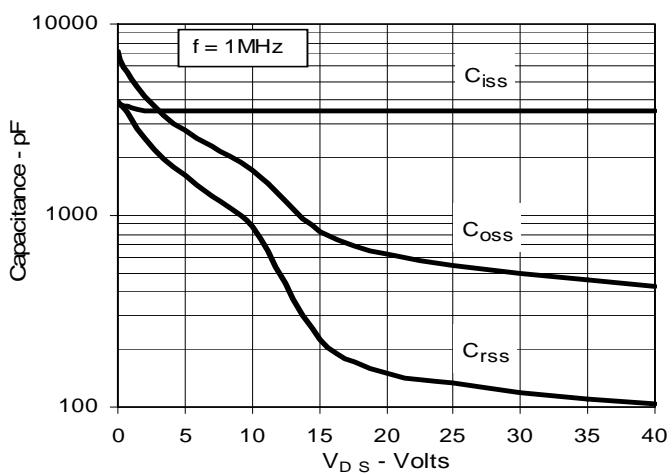
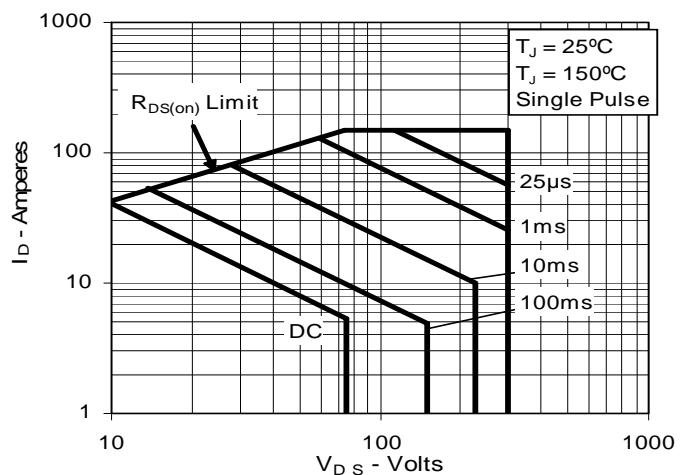
Fig. 7. Input Admittance

Fig. 8. Transconductance

Fig. 9. Source Current vs. Source-To-Drain Voltage

Fig. 10. Gate Charge

Fig. 11. Capacitance

Fig. 12. Forward-Bias Safe Operating Area


Fig. 13. Maximum Transient Thermal Impedance

